





40V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| V _{(BR)DSS} | R _{DS(on)} | I _D T _A = 25°C | |
|----------------------|-------------------------------|---|--|
| 40V | 8.5mΩ @ V _{GS} = 10V | 27.6A | |
| | 14mΩ @ V _{GS} = 4.5V | 21.5A | |

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- Power management functions

Features and Benefits

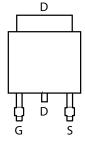
- · Low on-resistance
- · Fast switching speed
- "Green" component and RoHS compliant (Note 1)

Mechanical Data

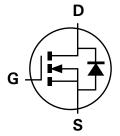
- Case: TO252-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Below
 Ordering Information: See Below
 Weight: 0.33 grams (approximate)







PIN OUT -TOP VIEW



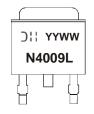
Equivalent Circuit

Ordering Information (Note 1)

| Product | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel | |
|---------------|---------|--------------------|-----------------|-------------------|--|
| DMN4009LK3-13 | N4009L | 13 | 16 | 2,500 | |

Note:

Marking Information



J;| = Manufacturer's Marking
N4009L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last two digits of year (ex: 09 = 2009)
WW = Week (01-52)

^{1.} Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.





Maximum Ratings @T_A = 25°C unless otherwise specified

| Cha | racteristic | | Symbol | Symbol Value | |
|---|----------------|-------------------------------|-----------------|--------------|---|
| Drain-Source voltage | | | V_{DSS} | 40 | V |
| Gate-Source voltage | | | V _{GS} | ±20 | V |
| | | (Note 3) | I _D | 27.6 | |
| Continuous Drain current | $V_{GS} = 10V$ | T _A =70°C (Note 3) | | 22.1 | Α |
| | | (Note 2) | | 18.0 | |
| Pulsed Drain current V _{GS} = 10V | | (Note 4) | I _{DM} | 96.6 | Α |
| Continuous Source current (Body diode) (Note 3) | | | I _S | 13.2 | Α |
| Pulsed Source current (Body diode) (Note 4) | | | I _{SM} | 96.6 | А |

Thermal Characteristics @TA = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Unit | |
|---|----------------------------------|-----------------------------------|----------------------|------------|
| | (Note 2) | | 4.36 34.8 | |
| Power dissipation Linear derating factor | (Note 3) | P _D | 10.3 82.4 | W mW/°C |
| | (Note 5) | | 2.19 17.5 | |
| Thermal Resistance, Junction to Ambient | (Note 2) (Note 3) (Note 5) | $R_{	heta JA}$ | 28.6 12.1 57.0 | °C/W |
| Thermal Resistance, Junction to Lead | (Note 6) | R _θ JL | 0.85 | 1 |
| Operating and storage temperature range | • | T _J , T _{STG} | -55 to 150 | °C |

Notes:

- 2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is

- measured when operating in a steady-state condition.

 3. Same as note 2, except the device is measured at t ≤ 10 sec.

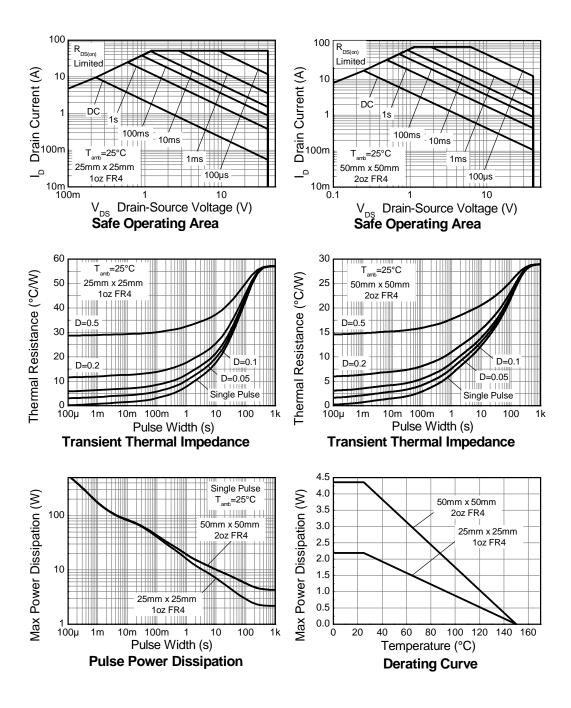
 4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.

 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when personnel in a steady state condition. measured when operating in a steady-state condition.
- 6. Thermal resistance from junction to solder-point (at the end of the drain lead).





Thermal Characteristics







Electrical Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | | | |
|--|----------------------|-----|------|------|-------|--|-----------------------|--|--|
| OFF CHARACTERISTICS | | | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 40 | _ | _ | V | $I_D = 250 \mu A, V_{GS}$ | = 0V | | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 0.5 | μА | V _{DS} = 40V, V _{GS} = | 0V | | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | V _{GS} = ±20V, V _{DS} | = 0V | | |
| ON CHARACTERISTICS | | | | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | 1.0 | _ | 3.0 | V | $I_D=250\mu A,\ V_{DS}=V_{GS}$ | | | |
| Static Drain-Source On-Resistance (Note 7) | В | | | 8.5 | mΩ | V _{GS} = 10V, I _D = 1 | 4A | | |
| Static Dialif-Source Off-Resistance (Note 7) | R _{DS (ON)} | _ | _ | 14 | 11122 | V _{GS} = 4.5V, I _D = 1 | 1A | | |
| Forward Transconductance (Notes 7 & 8) | g fs | _ | 35.3 | _ | S | V _{DS} = 15V, I _D = 12 | 2A | | |
| Diode Forward Voltage (Note 7) | V _{SD} | _ | 0.82 | 1.0 | V | I _S = 14A, V _{GS} = 0V | | | |
| Reverse recovery time (Note 8) | t _{rr} | | 141 | _ | ns | 1 111 di/dt 1000/ | | | |
| Reverse recovery charge (Note 8) | Q _{rr} | _ | 872 | _ | nC | I _S = 14A, di/dt= 100A/μs | | | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | | | |
| Input Capacitance | C _{iss} | _ | 2072 | _ | pF | | | | |
| Output Capacitance | Coss | _ | 338 | _ | pF | V _{DS} = 20V, V _{GS} = 0V f= 1MHz | | | |
| Reverse Transfer Capacitance | C _{rss} | _ | 193 | _ | pF | 1= 1101112 | | | |
| Total Gate Charge | Qg | _ | 21 | _ | nC | V _{GS} = 4.5V | | | |
| Total Gate Charge | Qg | _ | 42 | _ | nC | | V _{DS} = 20V | | |
| Gate-Source Charge | Q _{gs} | _ | 7.3 | _ | nC | V _{GS} = 10V I _D = 14A | | | |
| Gate-Drain Charge | Q_{gd} | _ | 10.7 | _ | nC | | | | |
| Turn-On Delay Time (Note 9) | t _{D(on)} | _ | 7.8 | _ | ns | | | | |
| Turn-On Rise Time (Note 9) | t _r | _ | 18.5 | _ | ns | V _{DD} = 20V, V _{GS} = 10V | | | |
| Turn-Off Delay Time (Note 9) | t _{D(off)} | _ | 37.3 | _ | ns | I_{D} = 14A, $R_{G} \cong 6.0\Omega$ | | | |
| Turn-Off Fall Time (Note 9) | t _f | _ | 14.9 | _ | ns | | | | |

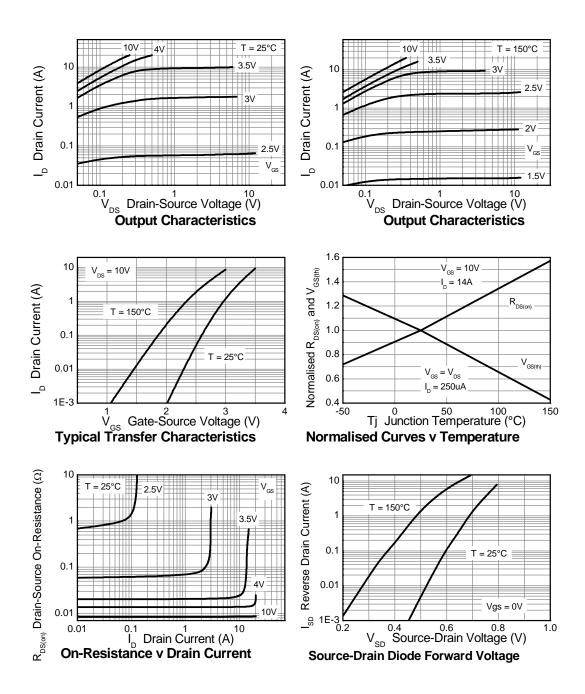
Notes:

- Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
 For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.



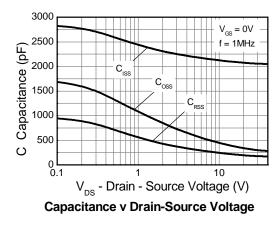


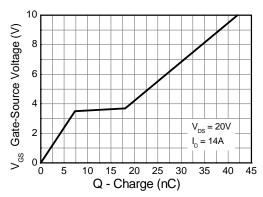
Typical Characteristics





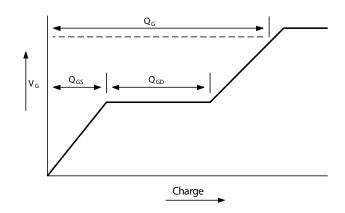
Typical Characteristics - continued





Gate-Source Voltage v Gate Charge

Test Circuits



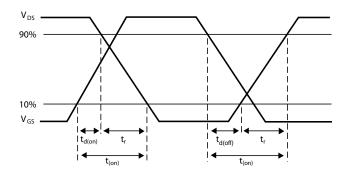
Current regulator

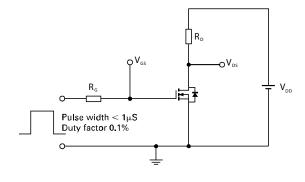
12V 0.2µF 50k D.U.T

Vos

Basic gate charge waveform

Gate charge test circuit



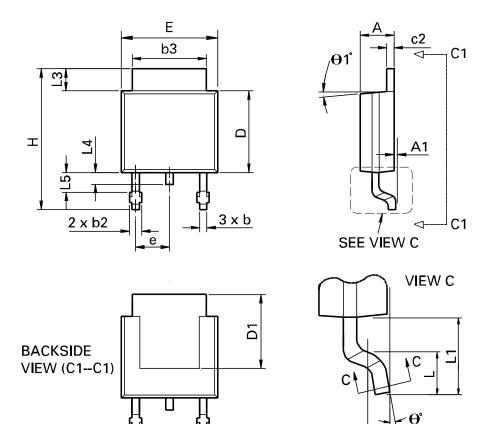


Switching time waveforms

Switching time test circuit

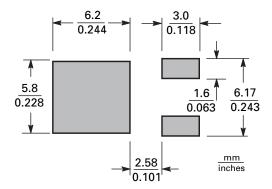


Package Outline Dimensions



| DIM | DIM Inches | | Millimeters | | DIM | Inches | | Millimeters | |
|------------|------------|-------|-------------|-------|-----|-----------|-------|-------------|-------|
| | Min | Max | Min | Max | | Min | Max | Min | Max |
| Α | 0.086 | 0.094 | 2.18 | 2.39 | е | 0.090 BSC | | 2.29 BSC | |
| A 1 | - | 0.005 | - | 0.127 | н | 0.370 | 0.410 | 9.40 | 10.41 |
| b | 0.020 | 0.035 | 0.508 | 0.89 | L | 0.055 | 0.070 | 1.40 | 1.78 |
| b2 | 0.030 | 0.045 | 0.762 | 1.14 | L1 | 0.108 REF | | 2.74 REF | |
| b3 | 0.205 | 0.215 | 5.21 | 5.46 | L2 | 0.020 BSC | | 0.508 BSC | |
| С | 0.018 | 0.024 | 0.457 | 0.61 | L3 | 0.035 | 0.065 | 0.89 | 1.65 |
| c2 | 0.018 | 0.023 | 0.457 | 0.584 | L4 | 0.025 | 0.040 | 0.635 | 1.016 |
| D | 0.213 | 0.245 | 5.41 | 6.22 | L5 | 0.045 | 0.060 | 1.14 | 1.52 |
| D1 | 0.205 | - | 5.21 | - | θ1° | 0° | 10° | 0° | 10° |
| E | 0.250 | 0.265 | 6.35 | 6.73 | θ° | 0° | 15° | 0° | 15° |
| E1 | 0.170 | - | 4.32 | - | - | - | - | - | - |

Suggested Pad Layout



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